Dual Schmitt-Trigger Inverter

The NLX2G14 MiniGate[™] is an advanced high-speed CMOS dual Schmitt-trigger inverter in ultra-small footprint.

The NLX2G14 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

The NLX2G14 can be used to enhance noise immunity or to square up slowly changing waveforms.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Low Power Dissipation: $I_{CC} = 1 \mu A \text{ (Max)}$ at $T_A = 25 \text{°C}$
- 24 Balanced Output Source and Sink Capability
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

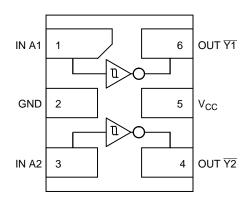


Figure 1. Pinout (Top View)

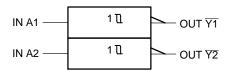


Figure 2. Logic Symbol

PIN ASSIGNMENT

FUNCTION TABLE A Ÿ L H

Н

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V _{CC}
6	OUT Y1



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MARKING DIAGRAMS



ULLGA6 1.0 x 1.0 CASE 613AD





ULLGA6 1.2 x 1.0 CASE 613AE





ULLGA6 1.45 x 1.0 CASE 613AF





UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.2 x 1.0 CASE 517AA





UDFN6 1.45 x 1.0 CASE 517AQ



T = Device Marking*
M = Date Code
* Rotated 90° clockwise

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

L

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
Io	DC Output Source/Sink Current	±50	mA	
I _{CC}	DC Supply Current Per Supply Pin	±100	mA	
I _{GND}	DC Ground Current per Ground Pin	±100	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case for 10 Second	nds	260	°C
TJ	Junction Temperature Under Bias	150	°C	
MSL	Moisture Sensitivity	Level 1		
F _R	Flammability Rating Oxygen	UL 94 V-0 @ 0.125 in		
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GN	±500	mA	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

- Tested to EIA/JESD22-A114-A.
 Tested to EIA/UESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free–Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V} $ $ V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V} $	0 0	No Limit No Limit	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}		T _A = 25 °C	;	T _A = -	+85°C	T _A = -{ +12	55°C to 5°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{T+}	Positive Threshold Voltage		1.65 2.3 2.7 3.0 4.5 5.5	0.6 1.0 1.2 1.3 1.9 2.2	1.0 1.5 1.7 1.9 2.7 3.3	1.4 1.8 2.0 2.2 3.1 3.6	0.6 1.0 1.2 1.3 1.9 2.2	1.4 1.8 2.0 2.2 3.1 3.6	0.6 1.0 1.2 1.3 1.9 2.2	1.4 1.8 2.0 2.2 3.1 3.6	>
V _T _	Negative Threshold Voltage		1.65 2.3 2.7 3.0 4.5 5.5	0.2 0.4 0.5 0.6 1.0	0.5 0.75 0.87 1.0 1.5	0.8 1.15 1.4 1.5 2.0 2.3	0.2 0.4 0.5 0.6 1.0	0.8 1.15 1.4 1.5 2.0 2.3	0.2 0.4 0.5 0.6 1.0	0.8 1.15 1.4 1.5 2.0 2.3	V
V _H	Hysteresis Voltage		1.65 2.3 2.7 3.0 4.5 5.5	0.1 0.25 0.3 0.4 0.6 0.7	0.48 0.75 0.83 0.93 1.2 1.4	0.9 1.1 1.15 1.2 1.5 1.7	0.1 0.25 0.3 0.4 0.6 0.7	0.9 1.1 1.15 1.2 1.5 1.7	0.1 0.25 0.3 0.4 0.6 0.7	0.9 1.1 1.15 1.2 1.5 1.7	V
V _{OH}	Minimum High-Level	$V_{IN} \le V_{T-MIN}$ $I_{OH} = -100 \mu A$	1.65– 5.5	V _{CC} - 0.1	V _{CC}		V _{CC} - 0.1		V _{CC} - 0.1		V
	Output Voltage	$\begin{array}{c} V_{IN} \leq V_{T-MIN} \\ I_{OH} = -4 \text{ mA} \\ I_{OH} = -8 \text{ mA} \\ I_{OH} = -12 \text{ mA} \\ I_{OH} = -16 \text{ mA} \\ I_{OH} = -24 \text{ mA} \\ I_{OH} = -32 \text{ mA} \end{array}$	1.65 2.3 2.7 3.0 3.0 4.5	1.29 1.9 2.2 2.4 2.3 3.8	1.52 2.1 2.4 2.7 2.5 4.0		1.29 1.9 2.2 2.4 2.3 3.8		1.29 1.8 2.1 2.3 2.2 3.7		
V _{OL}	Maximum Low-Level Output	$V_{IN} \ge V_{T+MAX}$ $I_{OL} = 100 \mu A$	1.65– 5.5		0	0.1		0.1		0.1	V
	Voltage	$\begin{array}{c} V_{IN} \geq V_{T+MAX} \\ I_{OH} = -4 \text{ mA} \\ I_{OH} = -8 \text{ mA} \\ I_{OH} = -12 \text{ mA} \\ I_{OH} = -16 \text{ mA} \\ I_{OH} = -24 \text{ mA} \\ I_{OH} = -32 \text{ mA} \end{array}$	1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.2 0.22 0.28 0.38 0.42	0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.4 0.5 0.5 0.55 0.65	
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 5.5 V	0 to 5.5			±0.1		±1.0		±1.0	μΑ
l _{OFF}	Power-Off Output Leakage Current	V _{OUT} = 5.5 V	0			1.0		10		10	μΑ
I _{CC}	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		10		10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$)

		V _{CC}	Test	т	' _A = 25 °(С	T _A = -	+85°C	T _A = - to +1		
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay, Input A to Output Y	2.3–2.7	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.8	4.3	7.4	1.8	8.1	1.8	9.1	ns
		3.0-3.6	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.5	3.3	5.0	1.5	5.5	1.5	6.5	
			$R_L = 500 \Omega,$ $C_L = 50 pF$	1.8	4.0	6.0	1.8	6.6	1.8	7.6	
		4.5–5.5	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.0	2.7	4.1	1.0	4.5	1.0	5.5	
			$R_L = 500 \Omega,$ $C_L = 50 pF$	1.2	3.2	4.9	1.2	5.4	1.2	6.4	
C _{IN}	Input Capacitance	5.5	V _{IN} = 0 V or V _{CC}		2.5						pF
C _{PD}	Power Dissipation Capacitance (Note 6)	3.3 5.5	10 MHz V _{IN} = 0 V or V _{CC}		11 12.5						pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

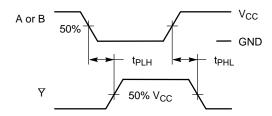
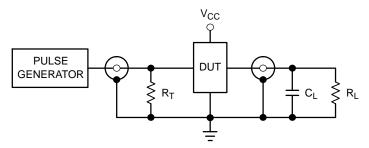


Figure 3. Switching Waveforms



 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

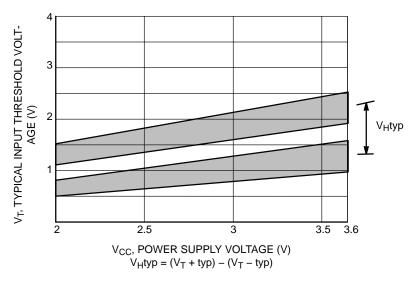
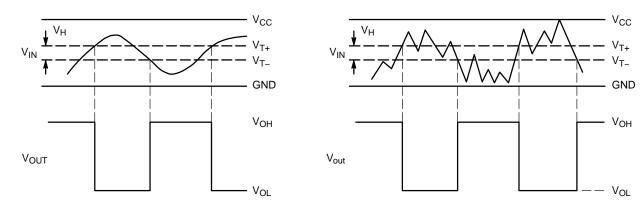


Figure 5. Typical Input Threshold, V_T+, V_T-versus Power Supply Voltage



(a) A Schmitt-Trigger Squares Up Inputs With Slow Rise and Fall Times

(b) A Schmitt-Trigger Offers Maximum Noise Immunity

Figure 6. Typical Schmitt-Trigger Applications

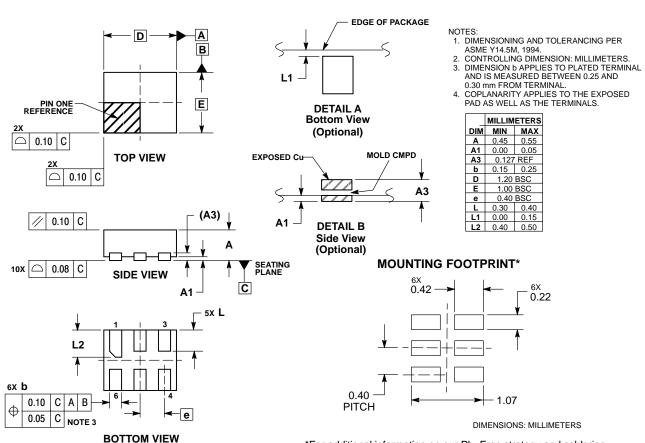
ORDERING INFORMATION

Device	Package	Shipping [†]
NLX2G14AMX1TCG	ULLGA6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G14BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G14CMX1TCG	ULLGA6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel
NLX2G14MUTCG In Development	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G14AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G14CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

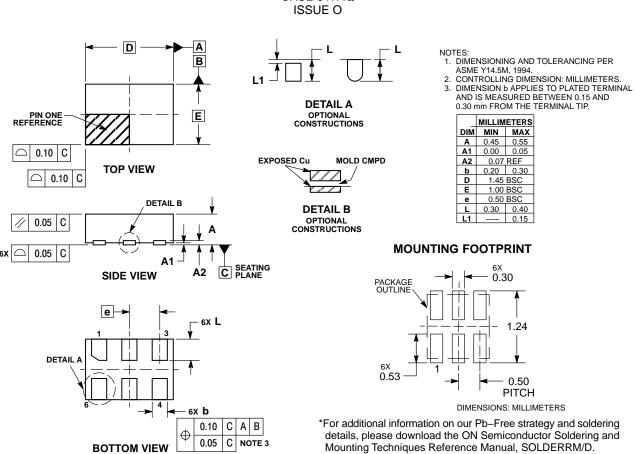
UDFN6, 1.2x1.0, 0.4P CASE 517AA ISSUE D



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

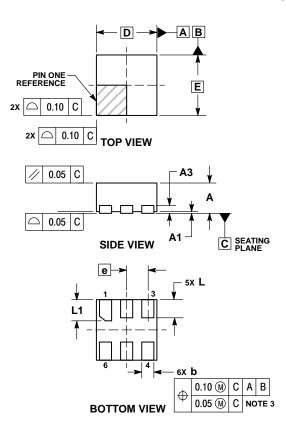
PACKAGE DIMENSIONS

UDFN6 1.45x1.0, 0.5P CASE 517AQ



PACKAGE DIMENSIONS

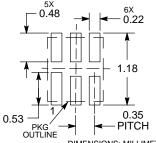
UDFN6 1.0x1.0, 0.35P CASE 517BX ISSUE O



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
 PACKAGE DIMENSIONS EXCLUSIVE OF
- BURRS AND MOLD FLASH.

	MILLIMETERS						
DIM	MIN	MAX					
Α	0.45	0.55					
A1	0.00	0.05					
A3	0.13	REF					
b	0.12	0.22					
D	1.00 BSC						
Е	1.00 BSC						
œ	0.35 BSC						
L	0.25	0.35					
L1	0.30	0.40					

RECOMMENDED SOLDERING FOOTPRINT*

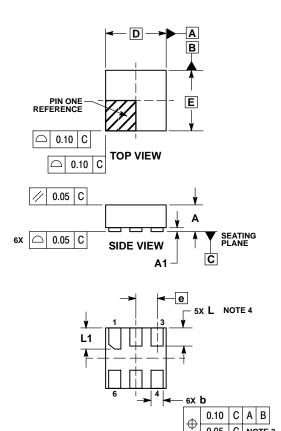


DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.0x1.0, 0.35P CASE 613AD **ISSUE A**



BOTTOM VIEW

0.05 С NOTE 3

NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

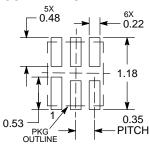
 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS						
DIM	MIN	MAX					
Α		0.40					
A1	0.00	0.05					
b	0.12	0.22					
D	1.00 BSC						
E	1.00 BSC						
е	0.35 BSC						
Ĺ	0.25	0.35					
L1	0.30	0.40					

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

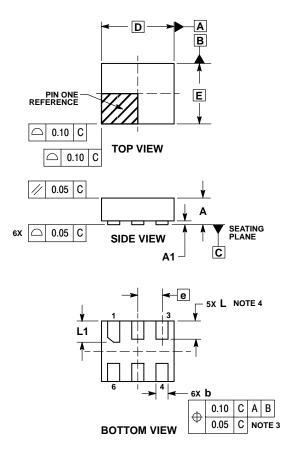


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

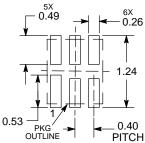
ULLGA6 1.2x1.0, 0.4P CASE 613AE **ISSUE A**



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 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS						
DIM	MIN	MAX					
Α		0.40					
A1	0.00	0.05					
ь	0.15	0.25					
ם	1.20	BSC					
Е	1.00	BSC					
Φ	0.40	BSC					
L	0.25	0.35					
L1	0.35 0.45						

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

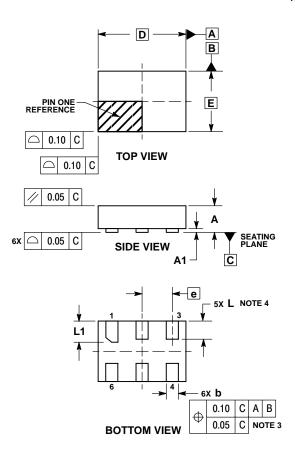


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.45x1.0, 0.5P CASE 613AF ISSUE A

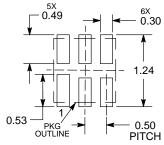


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
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 A MAXIMUM OF 0.05 PULL BACK OF THE
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$\overline{}$						
	MILLIMETERS					
DIM	MIN	MAX				
Α	-	0.40				
A1	0.00	0.05				
b	0.15	0.25				
D	1.45	BSC				
E	1.00	BSC				
е	0.50 BSC					
L	0.25	0.35				
L1	0.30	0.40				

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

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